

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

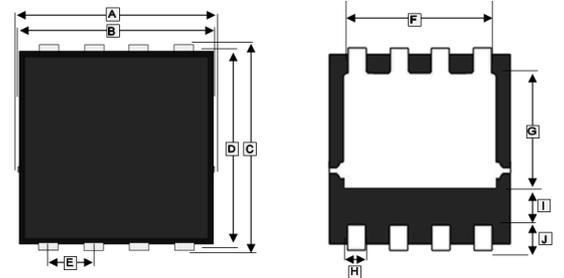
FEATURES

- Low $R_{DS(ON)}$ provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe DFN3x3-8PP saves board space
- Fast switching speed
- High performance trench technology

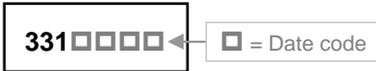
APPLICATION

DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

DFN3x3-8PP



MARKING



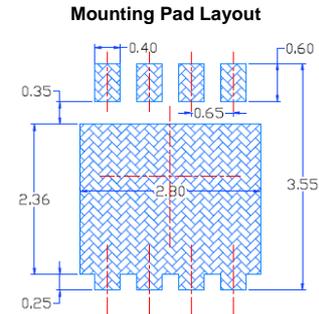
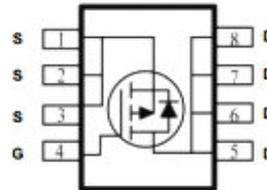
PACKAGE INFORMATION

Package	MPQ	Leader Size
DFN3x3-8PP	3K	13 inch

REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	3.00	3.40	G	1.78	1.98
B	3.00	3.20	H	0.25	0.35
C	3.25	3.45	I	0.35 TYP.	
D	3.00	3.20	J	0.60 TYP.	
E	0.65 BSC.		K	0.10	0.25
F	2.39	2.59	L	0.70	0.80

ORDER INFORMATION

Part Number	Type
SSPS7331P-C	Lead (Pb)-free and Halogen-free



*Dimensions in millimeters

MAXIMUM RATINGS ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	$T_A=25^\circ\text{C}$	-13.4
		$T_A=70^\circ\text{C}$	-10.2
Pulsed Drain Current ²	I_{DM}	-50	A
Continuous Source Current (Diode Conduction) ¹	I_S	-4.6	A
Total Power Dissipation ¹	P_D	$T_A=25^\circ\text{C}$	3.5
		$T_A=70^\circ\text{C}$	2
Operating Junction & Storage Temperature Range	T_J, T_{STG}	-55~150	$^\circ\text{C}$
Thermal Resistance Ratings			
Thermal Resistance Junction-Ambient (Max.) ¹	$R_{\theta JA}$	$t \leq 10\text{sec}$	35
		Steady State	81

Notes:

1. Surface Mounted on 1" x 1" FR-4 Board.
2. Pulse width limited by maximum junction temperature.

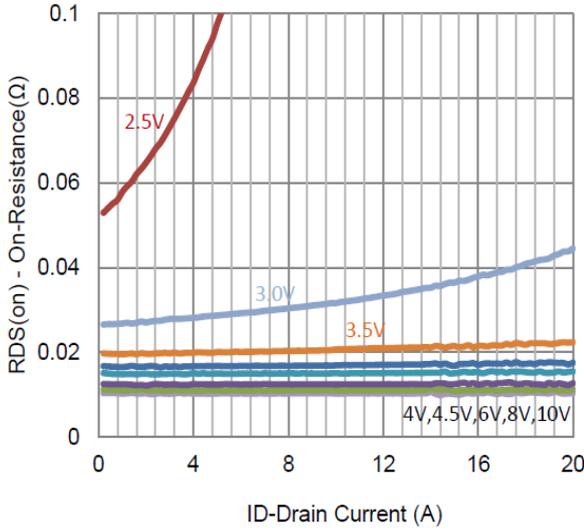
ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Gate-Threshold Voltage	$V_{GS(th)}$	-1	-	-	V	$V_{DS}=V_{GS}$, $I_D = -250\mu\text{A}$
Gate-Body Leakage Current	I_{GSS}	-	-	± 100	nA	$V_{DS}=0$, $V_{GS} = \pm 25\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}	-	-	-1	μA	$V_{DS} = -24\text{V}$, $V_{GS}=0$
		-	-	-25		$V_{DS} = -24\text{V}$, $V_{GS}=0$, $T_J=55^\circ\text{C}$
On-State Drain Current ¹	$I_{D(on)}$	-6.7	-	-	A	$V_{DS} = -5\text{V}$, $V_{GS} = -10\text{V}$
Drain-Source On-Resistance ¹	$R_{DS(ON)}$	-	-	13	m Ω	$V_{GS} = -10\text{V}$, $I_D = -10.7\text{A}$
		-	-	19		$V_{GS} = -4.5\text{V}$, $I_D = -8.9\text{A}$
Forward Transconductance ¹	g_{fs}	-	25	-	S	$V_{DS} = -15\text{V}$, $I_D = -10.7\text{A}$
Diode Forward Voltage	V_{SD}	-	-0.75	-	V	$I_S = -2.3\text{A}$, $V_{GS}=0$
Input Capacitance	C_{iss}	-	2186	-	pF	$V_{DS} = -15\text{V}$ $V_{GS}=0\text{V}$ $f=1\text{MHz}$
Output Capacitance	C_{oss}	-	373	-		
Reverse Transfer Capacitance	C_{rss}	-	336	-		
Total Gate Charge	Q_g	-	34	-	nC	$V_{DS} = -15\text{V}$ $V_{GS} = -4.5\text{V}$ $I_D = -10.7\text{A}$
Gate-Source Charge	Q_{gs}	-	7.8	-		
Gate-Drain Charge	Q_{gd}	-	16	-		
Turn-On Delay Time	$T_{d(on)}$	-	8	-	nS	$V_{DD} = -15\text{V}$ $I_D = -10.7\text{A}$ $V_{GEN} = -10\text{V}$ $R_{GEN}=6\Omega$ $R_L=1.5\Omega$
Rise Time	T_r	-	50	-		
Turn-Off Delay Time	$T_{d(off)}$	-	96	-		
Fall Time	T_f	-	59	-		

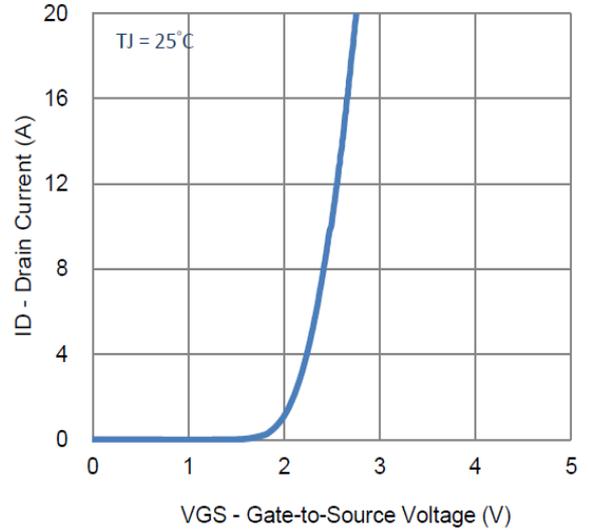
Note:

1. Pulse test: $P_w \leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

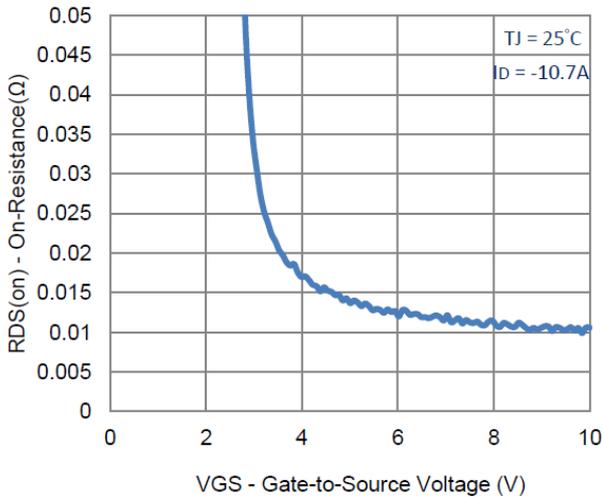
CHARACTERISTIC CURVE



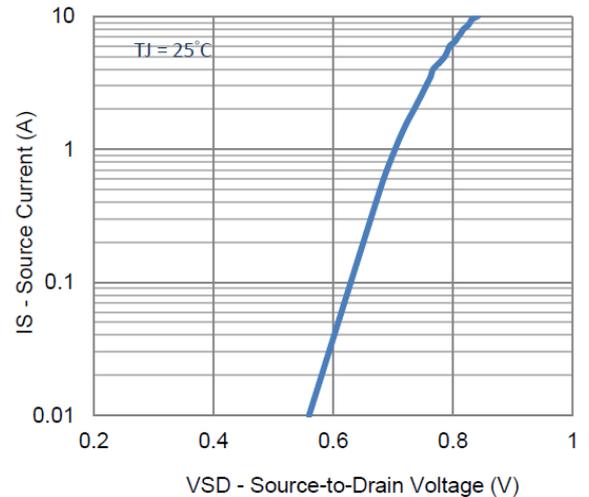
1. On-Resistance vs. Drain Current



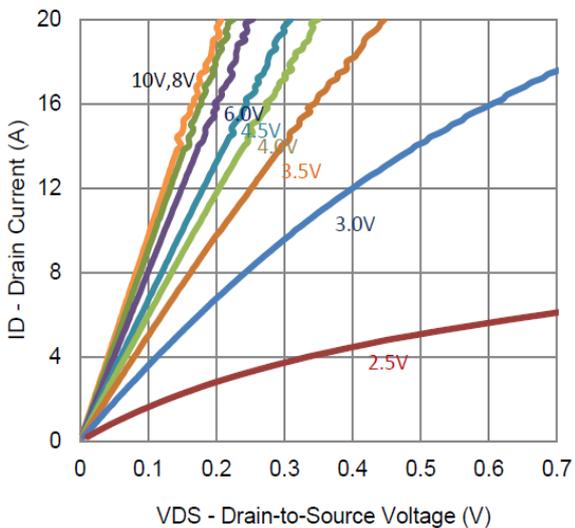
2. Transfer Characteristics



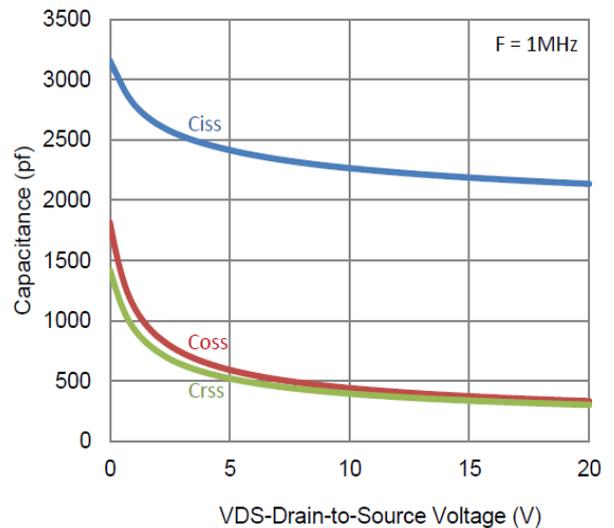
3. On-Resistance vs. Gate-to-Source Voltage



4. Drain-to-Source Forward Voltage

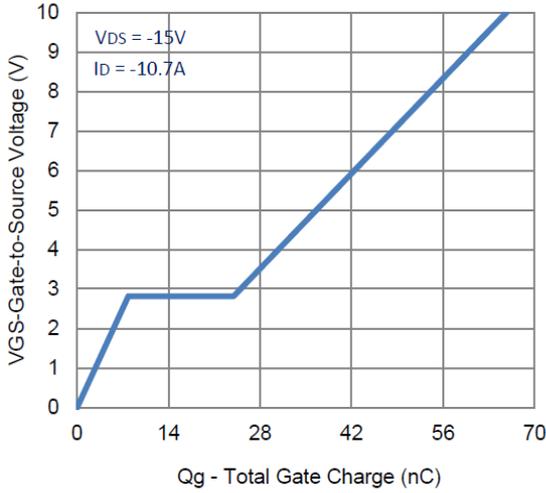


5. Output Characteristics

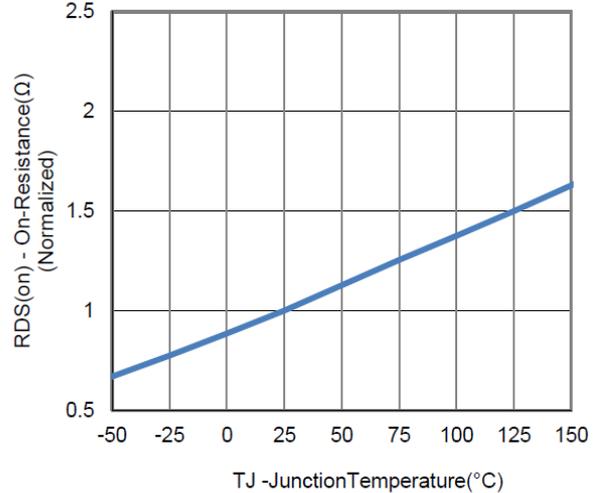


6. Capacitance

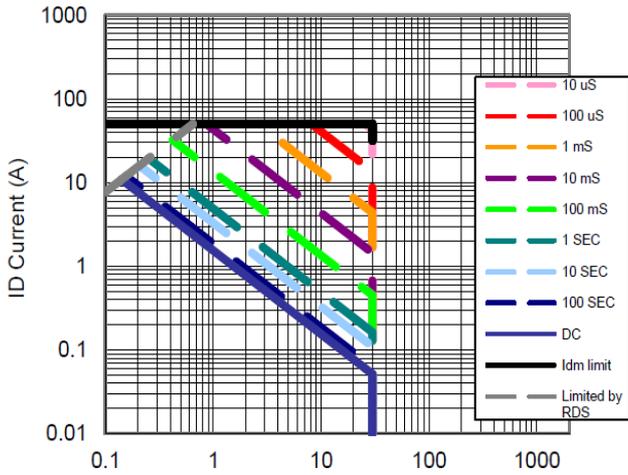
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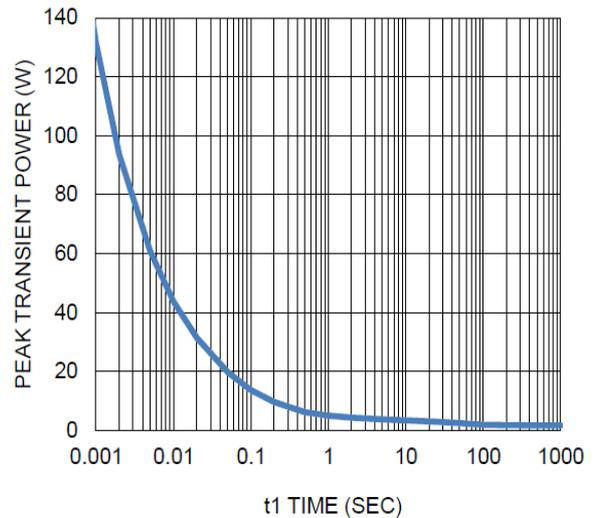
7. Gate Charge



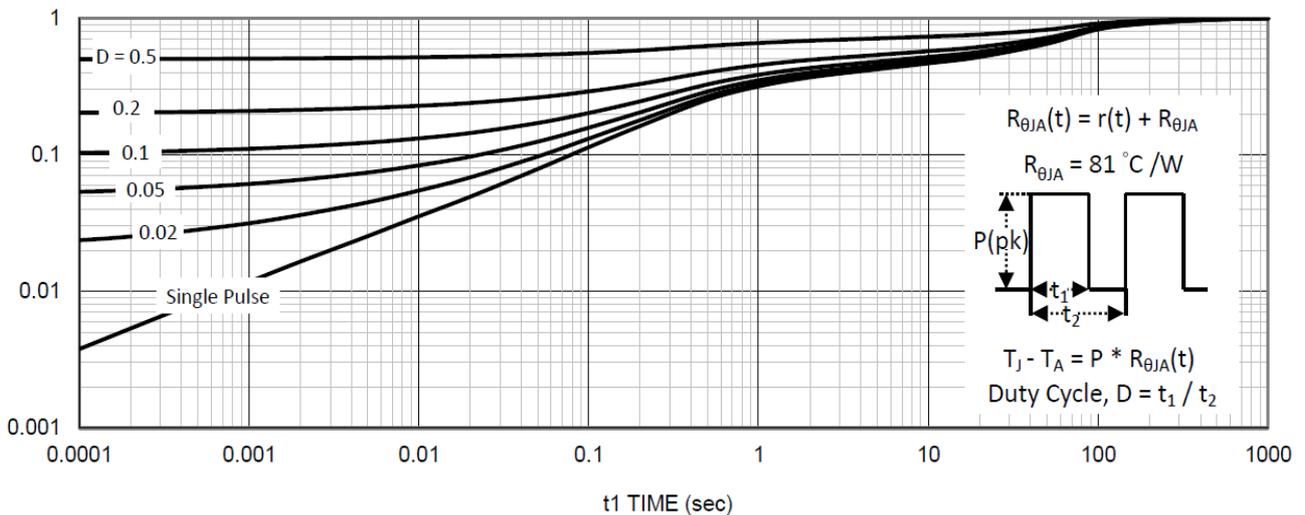
8. Normalized On-Resistance Vs Junction Temperature



9. Safe Operating Area



10. Single Pulse Maximum Power Dissipation



11. Normalized Thermal Transient Junction to Ambient